grounding conductor plate 13, the first conductor plate 2, and the second conductor plate 3 to forcibly conjoin them together, and in final stage, the aforesaid components are further engaged using the fixing screws 5. With this structure, the IC package structure of the present invention is characterized in possessing a large heat dissipation area and minimized course of the grounding conductor, besides, the effect of heat dissipation is further enhanced by forming tow layers of conductor plates 2 and 3. As a result, the IC package constructed according to the present invention achieves most optimistic heat dissipation effect.

In short, it emerges from the above description that the invention has several noteworthy advantages, in particular:

1.That the grounding effect, heat dissipation, performance and quality are the best of all equivalents.

2.The the easily assembled structure results in a low cost maintenance and components replacement.

Those who are skilled in the art will readily perceive how to modify the invention. Therefore, the appended claims are to be construed to cover all equivalent structures which fall within the true scope and spirit of the invention.